SCES075D - JUNE 1996 - REVISED DECEMBER 2002

- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High Drive (-12/12 mA at 3.3-V V_{CC})
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Output Ports Have Equivalent 30-Ω Series Resistors, So No External Resistors Are Required
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54ALVTHR16245 . . . WD PACKAGE SN74ALVTHR16245 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)

	<u> </u>		
1DIR	, U	48	1 <u>0E</u>
			_
1B1		47	1A1
1B2 l		46	1A2
GND		L	GND
1B3 [44	1A3
1B4 [6	43	1A4
v _{cc} [7	42] v _{cc}
1B5 [8	41	1A5
1B6 [9	40	1A6
GND[10	39] GND
1B7 [11	38	1A7
1B8 [12	37	1A8
2B1 [13	36	2A1
2B2	14	35	2A2
GND	15	34] GND
2B3 [16	33	2A3
2B4	17	32	2A4
V _{CC} [18	31] v _{cc}
2B5 [19	30	2A5
2B6 [20		2A6
GND[] GND
2B7 [22		2A7
2B8 [23		2A8
2DIR	24	25	2 <mark>OE</mark>
	Ь		

description/ordering information

The 'ALVTHR16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

TA	PACKAGET		I PACKAGET I		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tape and reel	SN74ALVTHR16245LR	ALVTHR16245		
4000 1- 0500	TSSOP – DGG	Tape and reel	SN74ALVTHR16245GR	ALVTHR16245		
–40°C to 85°C	TVSOP – DGV	Tape and reel	SN74ALVTHR16245VR	TR245		
	VFBGA – GQL	Tape and reel	SN74ALVTHR16245KR	TR245		
−55°C to 125°C	CFP – WD	Tube	SNJ54ALVTHR16245W	SNJ54ALVTHR16245W		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.



SCES075D - JUNE 1996 - REVISED DECEMBER 2002

description/ordering information (continued)

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

All outputs are designed to sink up to 12 mA, and include equivalent $30-\Omega$ resistors to reduce overshoot and undershoot.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN74ALVTHR16245 . . . GQL PACKAGE (TOP VIEW)

1 2 3 4 5 6 000000 Α 000000 В 000000 С OOOOOOD CYCLE PHE O O Ε $\bigcirc \bigcirc$ CCF 000000 G 000000 Н 000000 J 000000

terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
C	1B4	1B3	VCC	VCC	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCC	VCC	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2OE
	NO N		•	•	•	•

NC - No internal connection

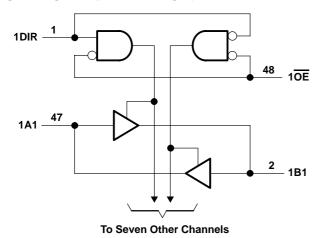
FUNCTION TABLE (each 8-bit section)

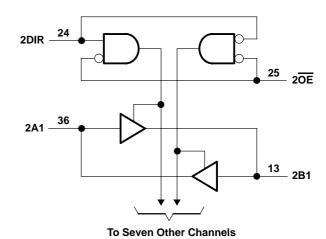
INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation



SCES075D - JUNE 1996 - REVISED DECEMBER 2002

logic diagram (positive logic)





Pin numbers shown are for the DGG, DGV, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	%?	0.5 V to 7 V
Voltage range applied to any output in the high	or power-off state, V _O (see Note 1)	0.5 V to 7 V
Output current in the low state, IO: SN54ALVT	HR16245	96 mA
SN74ALVTI	HR16245	128 mA
Output current in the high state, Io: SN54ALVT	HR16245	–48 mA
SN74ALVT	HR16245	–64 mA
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DGG package	70°C/W
	DGV package	58°C/W
	DL package	63°C/W
	GQL package	42°C/W
Storage temperature range, T _{sta}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SCES075D - JUNE 1996 - REVISED DECEMBER 2002

recommended operating conditions, V_{CC} = 2.5 V \pm 0.2 V (see Note 3)

			SN54A	LVTHR	6245	SN74A	LVTHR	16245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNII
VCC	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	High-level input voltage			,	7	1.7			V
V_{IL}	Low-level input voltage			S	0.7			0.7	V
VI	Input voltage			Vcc	5.5	0	VCC	5.5	V
loh	High-level output current			7	-6			-8	mA
loL	Low-level output current			5	6			12	mA
Δt/Δν	Input transition rise or fall rate Outputs enabled		0/0/	7	10			10	ns/V
Δt/ΔV _{CC}	C Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

recommended operating conditions, V_{CC} = 3.3 V \pm 0.3 V (see Note 3)

		SN54ALVTHR1	6245	SN74A	LVTHR1	16245	UNIT
		MIN TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage	3	3.6	3		3.6	V
V _{IH}	High-level input voltage	2	A	2			V
V_{IL}	Low-level input voltage	~O'S	0.8			0.8	V
VI	Input voltage	0 VCC	5.5	0	VCC	5.5	V
ІОН	High-level output current	1	-8			-12	mA
loL	Low-level output current	27/	8			12	mA
Δt/Δν	Input transition rise or fall rate Outputs enabled	702	10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200			μs/V
T _A	Operating free-air temperature	– 55	125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SCES075D - JUNE 1996 - REVISED DECEMBER 2002

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

	DAMETER	TEST OF	NUDITIONS	SN54A	LVTHR	16245	SN74	ALVTHR'	16245	UNIT	
	ARAMETER	1551 CC	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII	
٧ıĸ		V _{CC} = 2.3 V,	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.	2		VCC-0	.2			
Vон		V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.7						V	
		VCC = 2.3 V	$I_{OH} = -8 \text{ mA}$				1.7				
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OL} = 100 μA			0.2			0.2		
VOL		V _{CC} = 2.3 V	$I_{OL} = 6 \text{ mA}$			0.7				V	
		VCC = 2.3 V	$I_{OL} = 12 \text{ mA}$						0.7		
	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V			10			10		
Ц			V _I = 5.5 V			<u>2</u> 0			20	μΑ	
A or B ports	V _{CC} = 2.7 V	VI = VCC		Š	1	1		1			
			V _I = 0		27	– 5			- 5		
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		3				±100	μΑ	
I _{BHL} ‡		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V	40	115			115		μΑ	
IBHH§		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V		-10			-10		μΑ	
IBHLO	1	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300	1		300			μΑ	
Івнно) [#]	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ	
{IEX}		$V{CC} = 2.3 \text{ V},$	V _O = 5.5 V			125			125	μΑ	
IOZ(PL	J/PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}} \text{ V}$ V _I = GND or V _{CC} , $\overline{\text{OE}}$ =	to V _{CC} , don't care			±100			±100	μА	
ICC		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1		
		$I_{O}=0$,	Outputs low		2.5	4.5		2.5	4.5	mA	
		$V_1 = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1		
Ci		$V_{CC} = 2.5 \text{ V},$	V _I = 2.5 V or 0		3.5			3.5		pF	
C _{io}		$V_{CC} = 2.5 \text{ V},$	$V_0 = 2.5 \text{ V or } 0$		8			8		pF	

 $^{^{\}dagger}_{\cdot}$ All typical values are at VCC = 2.5 V, TA = 25°C.

[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

 $[\]P$ An external driver must source at least $I_{\mbox{\footnotesize{BHLO}}}$ to switch this node from low to high.

[#]An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

SCES075D - JUNE 1996 - REVISED DECEMBER 2002

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER		TEST CO	TEST CONDITIONS		LVTHR	16245	SN74ALVTHR16245			UNIT
PA	RAWETER	1231 00	CHOITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
٧ıK		$V_{CC} = 3 V$,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.	2		VCC-0.	2		
Vон		V _{CC} = 3 V	$I_{OH} = -8 \text{ mA}$	2						V
		VCC = 3 V	I _{OH} = -12 mA				2			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
VOL		V _{CC} = 3 V	I _{OL} = 8 mA			0.8				V
			I _{OL} = 12 mA						0.8	
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
		$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10	
lį			V _I = 5.5 V			20			20	μΑ
	A or B ports	VCC = 3.6 V	$\Lambda^{I} = \Lambda^{CC}$			1		-	1	
			V _I = 0		<u> </u>	-5			- 5	
loff		V _{CC} = 0,	V_I or $V_O = 0$ to 4.5 V		4	75		-	±100	μΑ
I _{BHL} ‡		V _{CC} = 3 V,	V _I = 0.8 V	75	30	-4	75			μΑ
IBHH§	•	V _{CC} = 3 V,	V _I = 2 V	-75		Q Y	-75			μΑ
IBHLO		V _{CC} = 3.6 V,	$V_I = 0$ to V_{CC}	500	W.		500			μΑ
^І ВННО [‡]	#	V _{CC} = 3.6 V,	$V_I = 0$ to V_{CC}	-500			-500			μΑ
_{IEX}		V _{CC} = 3 V,	V _O = 5.5 V			125			125	μΑ
IOZ(PU	//PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = 0.5 \text{ V}$ V _I = GND or V _{CC} , $OE = 0.5 \text{ V}$	to V _{CC} , don't care			±100			±100	μΑ
		V _{CC} = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1	
ICC		$I_0 = 0$,	Outputs low		3.5	5		3.5	5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.07	0.1		0.07	0.1	
∆ICC□		$V_{CC} = 3 \text{ V to } 3.6 \text{ V, One}$ Other inputs at V_{CC} or G	input at V _{CC} – 0.6 V, ND			0.4			0.4	mA
Ci		V _{CC} = 3.3 V,	V _I = 3.3 V or 0		3.5			3.5		pF
C _{io}		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		8			8		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[¶] An external driver must source at least I_{BHLO} to switch this node from low to high.

[#] An external driver must sink at least IBHHO to switch this node from high to low.

 $[\]parallel$ Current into an output in the high state when $V_O > V_{CC}$

^{*}High-impedance state during power up or power down

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

SCES075D - JUNE 1996 - REVISED DECEMBER 2002

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

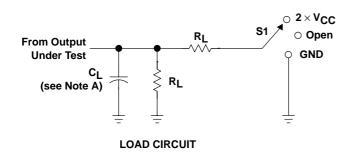
DADAMETED	FROM	ТО	SN54ALV	THR16245	SN74ALV	THR16245	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	A or B	B or A	0.5	4.3	0.5	4.3	20
^t PHL	AUIB	BULA	0.5	3.7	0.5	3.7	ns
^t PZH	ŌĒ	A or B	1.8	5.6	1.8	5.6	ns
^t PZL	OE	AUB	1.6	4.7	1.6	4.7	115
^t PHZ	OE	A or B	1.7	5	1.7	5	ns
^t PLZ		7.01.0	1.4	4.4	1.4	4.4	113

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALV	THR16245	SN74ALV	THR16245	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	ONIT	
tplH	A or B	B or A	0.5	3.7	0.5	3.7	ns	
^t PHL	AOIB	BUIA	0.5	3.9	0.5	3.9	115	
^t PZH	ŌĒ	A or B	1.3	5.2	1.3	5.2	ns	
^t PZL	OE	AOID	1.3	4	1.3	4	115	
^t PHZ	ŌĒ	A or B	2	5.1	2	5.1	ns	
^t PLZ	OE	COLD	1.5	4.8	1.5	4.8	113	

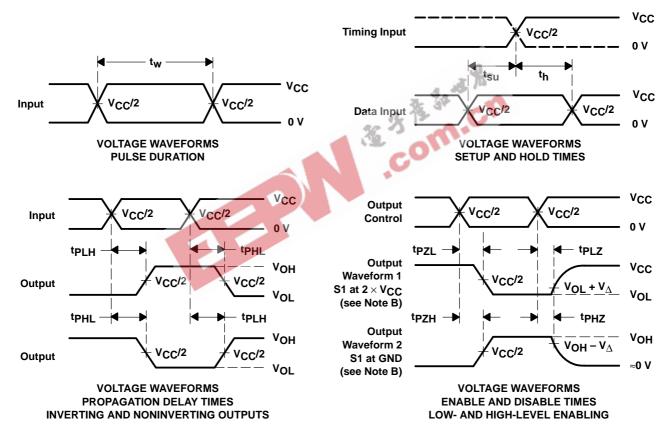
SCES075D - JUNE 1996 - REVISED DECEMBER 2002

PARAMETER MEASUREMENT INFORMATION



TEST	S 1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V
3.3 V ±0.3 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

5-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVTHR16245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245ZQLR	ACTIVE	VFBGA	ZQL	56	1000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74ALVTHR16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245KR	ACTIVE	VFBGA	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74ALVTHR16245LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

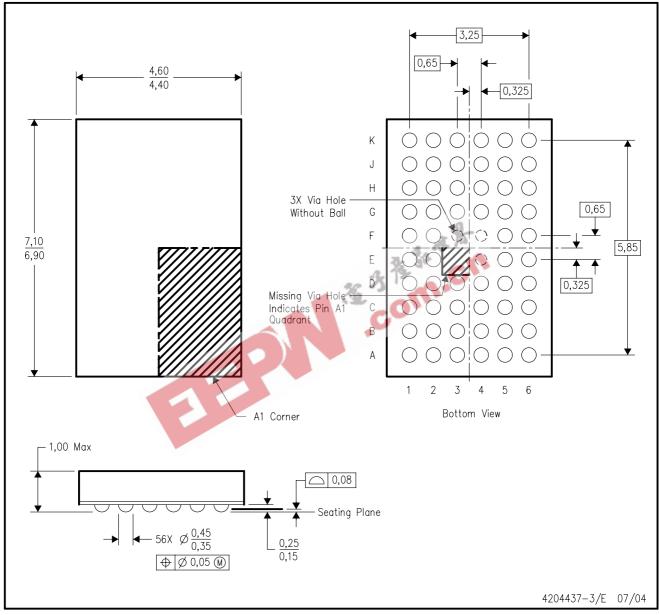
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

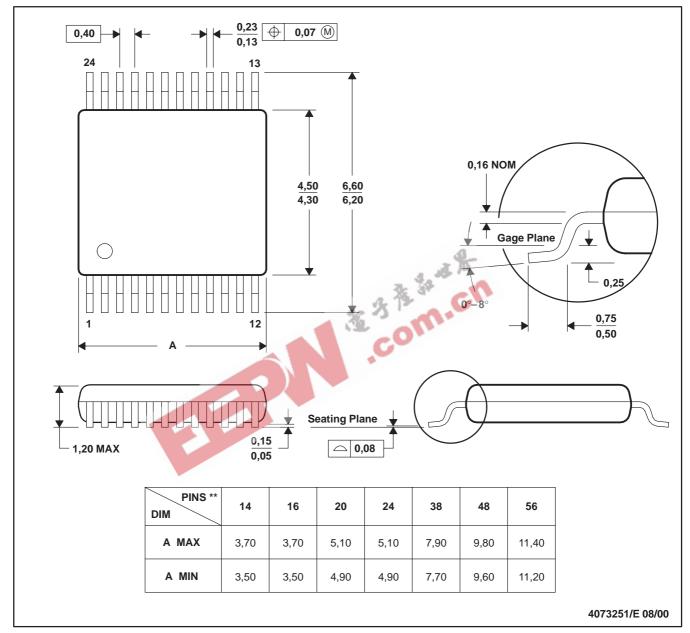
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

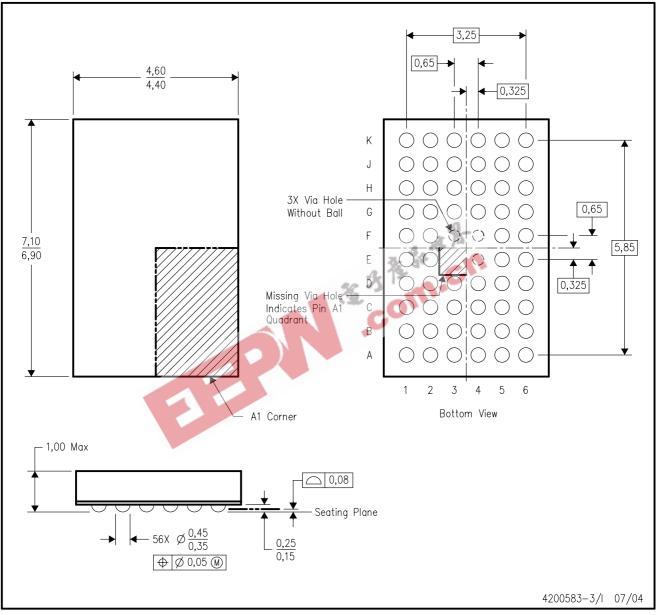
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

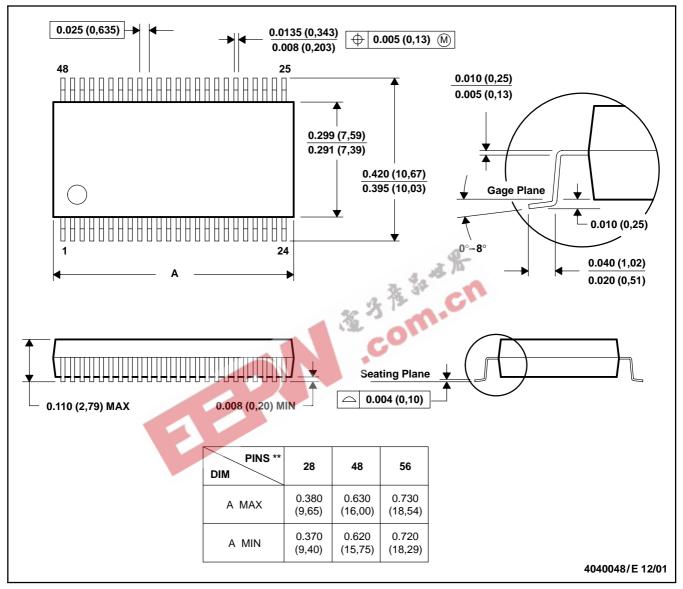
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



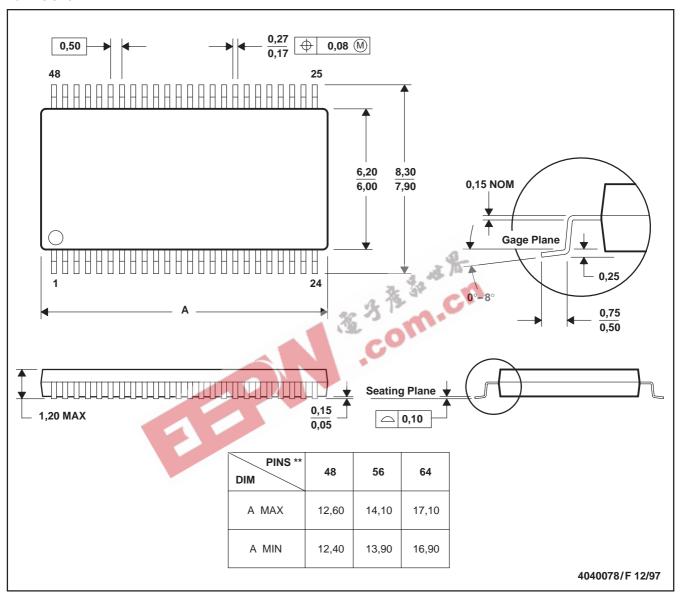
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated